D2661, APRIL 1982-REVISED MARCH 1988

- Fully Buffered to Offer Maximum Isolation from External Disturbance
- Package Options Include Plastic "Small Outline" Packages, Ceramic Chip Carriers and Flat Packages, and Plastic and Ceramic DIPs
- Dependable Texas Instruments Quality and Reliability

#### description

These devices contain two independent J-K negative-edge-triggered flip-flops. A low level at the preset and clear inputs sets or resets the outputs regardless of the levels of the other inputs. When preset and clear are inactive (high), data at the J and K inputs meeting the setup time requirements are transferred to the outputs on the negative-going edge of the clock pulse. Clock triggering occurs at a voltage level and is not directly related to the rise time of the clock pulse. Following the hold time interval, data at the J and K inputs may be changed without affecting the levels at the outputs. These versatile flip-flops can perform as toggle flip-flops by tying J and K high.

The SN54LS112A and SN54S112 are characterized for operation over the full military temperature range of ~55°C to 125°C. The SN74LS112A and SN74S112A are characterized for operation from 0°C to 70°C.

#### FUNCTION TABLE (each flip-flop)

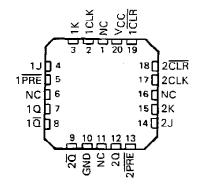
	INI	PUTS			ουπ	PUTS
PRE	CLR	CLK	J	K	a	Q
L	Н	X	Х	Х	Н	L
н	L	×	Х	X	L	Н
L	L	×	х	Х	H <sup>†</sup>	H <sup>†</sup>
н	н	1	L	L	ΩO	₫₀
H	Н	1	Н	L	Н	L
Н	H	1	L	н	L	н
Н	Н	1	Н	н	TOG	GLE
Н	<u> H</u>	Н	_ X	х	αo	₫o

<sup>&</sup>lt;sup>†</sup> The output levels in this configuration are not guaranteed to meet the minimum levels for V<sub>OH</sub> if the lows at preset and clear are near V<sub>IL</sub> minimum. Furthermore, this configuration is nonstable; that is, it will not persist when either preset or clear returns to its inactive (high) level.

SN54LS112A, SN54S112 . . . J OR W PACKAGE SN74LS112A, SN74S112A . . . D OR N PACKAGE (TOP VIEW)

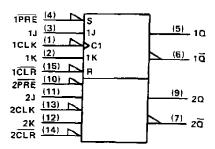
_	_		
1CLK[	]1	$\cup_{16}$	□vcc
1K [	]2	15	1 CLR
1J[	]3	14	2CLR
1PRE	]4	13	2CLK
10[	]5	12	<u></u> 2κ
10[	]6	11	2J
20 [	7	10	2PRE
GND [	8	9	20

SN54LS112A, SN54S112...FK PACKAGE (TOP VIEW)



NC-No internal connection

#### logic symbol‡

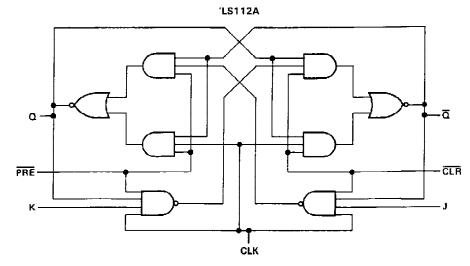


<sup>&</sup>lt;sup>‡</sup>This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

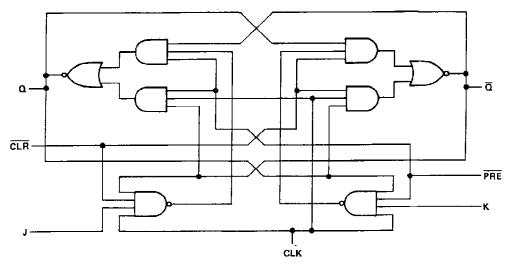
Pin numbers shown are for D, J, N, and W packages.

## SN54LS112A, SN54S112, SN74LS112A, SN74S112A DUAL J-K NEGATIVE-EDGE-TRIGGERED FLIP-FLOPS WITH PRESET AND CLEAR

### logic diagrams (positive logic)

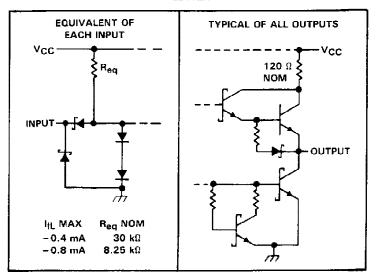


#### SN54S112, SN74LS112A

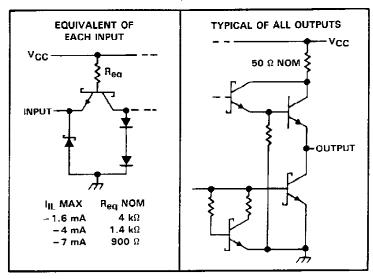


### schematics of inputs and outputs

'LS112A



#### SN54S112, SN74S112A



#### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, VCC (see Note 1)	7 V
Input voltage: 'LS112A 7	7 V
SN54LS112, SN74LS112A	5 V
Operating free-air temperature range: SN54'	§°C
SN74' 0°C to 70	)°C
Storage temperature range65 °C to 150	)°C

NOTE 1: Voltage values are with respect to network ground terminal.

#### SN54LS112A, SN74LS112A DUAL J-K NEGATIVE-EDGE-TRIGGERED FLIP-FLOPS WITH PRESET AND CLEAR

#### recommended operating conditions

			SN54LS112A			SN	74LS11	2A	
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Vcc	Supply voltage		4.5	5	5.5	4.75	5	5.25	V
ViH	High-level input voltage		2			2			V
VIL	Low-level input voltage				0.7			0.8	٧
Юн	High-level output current				-0.4			-0.4	mΑ
lOL_	Low-level output current				4			8	mA
fclock	Clock frequency		0	-	30	0		30	MHz
•	Pulse duration	CLK high	20			20			
t <sub>W</sub>	ruise duration	PRE or CLR low	25			25	<u></u>		ns
		Data high or low	20		**	20			
t <sub>su</sub>	Set up time-before CLK↓	CLR inactive	25			25			ns
		PRE inactive	20			20			
th	Hold time-data after CLK1		0			0			Π\$
TA	Operating free-air temperature		- 55		125	0		70	°C

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	BANETER	TEST	CONDITIONS†		SI	154LS11	2A	SI	174LS11	2A	
Ρ,	ARAMETER	IEST	CONDITIONS		MIN	TYP!	MAX	MIN	TYP‡	MAX	UNIT
$v_{lK}$		V <sub>CC</sub> = MIN,	I <sub>I</sub> = -18 mA				-1.5			1.5	V
Vон		V <sub>CC</sub> = MIN, I <sub>OH</sub> = -0.4 mA	$V_{IH} = 2 V$ ,	V <sub>IL</sub> = MAX,	2.5	3.4		2.7	3.4		V
.,		V <sub>CC</sub> = MIN, I <sub>OL</sub> = 4 mA	V <sub>IL</sub> = MAX,	V <sub>IH</sub> = 2 V,		0.25	0.4		0.25	0.4	v
VOL		V <sub>CC</sub> = MIN, I <sub>OL</sub> = 8 mA	$V_{IL} = MAX,$	V <sub>IH</sub> = 2 V,					0.35	0.5	
	J or K						0.1			0.1	
f <sub>l</sub>	CLR or PRE	VCC = MAX,	$V_I = 7 V$				0.3			0.3	mA
	CLK						0.4			0.4	
	J or K						20			20	
ΉΗ	CLR or PRE	V <sub>CC</sub> = MAX,	$V_{\parallel}$ = 2.7 $\vee$		-		60			60	μА
	CLK						80			80	Ĺ
1	J or K	Vcc = MAX,	Vi = 0 4 V				-0.4			-0.4	mA
ll .	All other	ACC - IAIWY	V1 = 0.4 V				-0.8			-0.8	
los §		VCC = MAX.	see Note 2		20		- 100	- 20		- 100	mΑ
ICC (T	otal)	V <sub>CC</sub> = MAX,	see Note 3			4	6		4	6	mА

<sup>&</sup>lt;sup>†</sup> For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

<sup>&</sup>lt;sup>‡</sup>All typical values are at V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25 °C.

Not more than one output should be shorted at a time, and the duration of the short-circuit should not exceed one second.

NOTES: 2. For certain devices where state commutation can be caused by shorting an output to ground, an equivalent test may be performed with  $V_0 = 2.25 \text{ V}$  and 2.125 V for the '54 family and the '74 family, respectively, with the minimum and maximum limits reduced to one half of their stated values.

<sup>3.</sup> With all outputs open, ICC is measured with the Q and  $\overline{Q}$  outputs high in turn. At the time of measurement, the clock input is grounded.

# switching characteristics, V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25 °C (see Note 4)

PARAMETER	FROM (INPUT)	TQ {OUTPUT)	TEST CO	NDITIONS	MIN	ТҮР	MAX	UNIT
fmax				<del></del>	30	45		MHz
t <b>P</b> LH	CLR. PRE or CLK	Q or Q	$R_L = 2 k\Omega$ ,	C <sub>L</sub> = 15 pF		15	20	กร
†PHL	CLM, PRE OF CLK	2012				15	20	пs

NOTE 4: Load circuits and voltage waveforms are shown in Section 1.

### SN54S112, SN74S112A DUAL J-K NEGATIVE EDGE-TRIGGERED FLIP-FLOPS WITH PRESET AND CLEAR

#### recommended operating conditions

			S	SN54S112			174611	2A	UNIT
			MIN	NOM	MAX	MIN	NOM	MAX	DINIT
VCC	Supply voltage		4.5	5	5.5	4.75	5	5.25	V
ViH	High-level input voltage	-	2			2			V
VIL	Low-level input voltage				0.8			0.8	٧
ЮН	High-level output current				- 1			<b>– 1</b>	mA
loL	Low-level output current				20			20	mΑ
		CLK high	6			6		.,,	
tw	Pulse duration	CLK low	6.5		- <b>-</b>	6.5			пѕ
		PRE or CLR low	8			8			
t <sub>su</sub>	Set up time-before CLK↓	Data high or low	7			7			กร
th	Hold time-data after CLK↓		0			0			ns
TA	Operating free-air temperature		-55		125	0		70	°C

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	DAMETED	TECT	CONDITIONS		5	N54S1	2	SI	N74S11	2 <b>A</b>	LIBUT
PA	RAMETER	IESI	CONDITIONS		MIN	TYP <sup>‡</sup>	MAX	MIN	TYP‡	MAX	UNIT
VIK		V <sub>CC</sub> = MIN,	lj = -18 mA				-1.2			-1.2	٧
VoH		V <sub>CC</sub> = MIN, I <sub>OH</sub> = -1 mA	V <sub>IH</sub> = 2 V,	VIL = MAX,	2.5	3.4		2.7	3.4		٧
VOL		V <sub>CC</sub> = MIN, I <sub>OL</sub> = 20 mA	V <sub>IH</sub> = 2 V,	V <sub>IL</sub> - 0.8 V,			0.5			0.5	V
I <sub>I</sub>			V <sub>1</sub> = 5.5 V				1			1	mA
1.	J or K	VCC = MAX.	V 27V				50			50	μА
ΉН	All other	T ACC = MINY	V  = 2.7 V				100			100	μπ
	Jor K						-1.6			-1.6	
	CLR <sup>§</sup>	],,	V 05V				<b>-7</b>			<b>-7</b>	mΑ
ΙΙΓ	PRE §	V <sub>CC</sub> = MAX,	VI = 0.5 V			•	-7	1		<b>-7</b>	MA
	CLK	1					-4			- 4	
los¶		V <sub>CC</sub> = MAX			-40	•	- 100	-40		~ 100	mA
ICC#		V <sub>CC</sub> = MAX,	see Note 3			15	25		15	25	mA

<sup>†</sup> For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

<sup>&</sup>lt;sup>‡</sup> All typical values are at  $V_{CC}$  = 5 V,  $T_A$  = 25 °C.

<sup>§</sup>Clear is tested with preset high and preset is tested with clear high.

Not more than one output should be shorted at a time, and the duration of the short-circuit should not exceed one second.

<sup>#</sup>Values are average per flip-flop.

NOTE 3: With all outputs open, I<sub>CC</sub> is measured with the Q and  $\overline{Q}$  outputs high in turn. At the time of measurement, the clock input is grounded.

# switching characteristics, VCC = 5 V, TA = 25 °C (see Note 4)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
f <sub>max</sub>				80	125		MHz
tPLH	PRE or CLR	Q or Q			4	7	กร
4	PRE or CLR (CLK high)	Q or Q	B. 200.0 0. 455		5	7	
tPHL	PRE or CLR (CLK low)	a or a	$R_L = 280 \Omega$ , $C_L = 15 pF$		5	7	ns
<sup>t</sup> PLH	CLK	Q or $\overline{\mathbf{Q}}$			4	7	ns
tPHL .	CER	Q 01 Q	<u> </u>		5	7	ns

NOTE 4: Load circuits and voltage waveforms are shown in Section 1.

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#### **PACKAGING INFORMATION**

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
JM38510/07102BEA	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/07102B EA	Samples
JM38510/07102BFA	ACTIVE	CFP	W	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 07102BFA	Samples
JM38510/30103B2A	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30103B2A	Samples
JM38510/30103BEA	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30103BEA	Samples
JM38510/30103BFA	ACTIVE	CFP	W	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30103BFA	Samples
M38510/07102BEA	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/07102B EA	Samples
M38510/07102BFA	ACTIVE	CFP	W	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 07102BFA	Sample
M38510/30103B2A	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30103B2A	Sample
M38510/30103BEA	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30103BEA	Sample
M38510/30103BFA	ACTIVE	CFP	W	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30103BFA	Sample
SN54LS112AJ	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54LS112AJ	Sample
SN54S112J	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54S112J	Sample
SN74LS112AD	ACTIVE	SOIC	D	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS112A	Sample
SN74LS112ADR	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS112A	Sample
SN74LS112ADRE4	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS112A	Sample
SN74LS112AN	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74LS112AN	Sample
SN74LS112ANSR	ACTIVE	SO	NS	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS112A	Sample

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Orderable Device	Status (1)	Package Type	Package Drawing		Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SN74S112AN	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74S112AN	Samples
SNJ54LS112AFK	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54LS 112AFK	Samples
SNJ54LS112AJ	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54LS112AJ	Samples
SNJ54LS112AW	ACTIVE	CFP	W	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54LS112AW	Samples
SNJ54S112FK	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54S 112FK	Samples
SNJ54S112J	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54S112J	Samples

**SNPB** 

N / A for Pkg Type

-55 to 125

SNJ54S112W

(1) The marketing status values are defined as follows:

SNJ54S112W

**ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

CFP

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

16

1

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

**ACTIVE** 

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

Non-RoHS

& Green

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

W

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

### PACKAGE OPTION ADDENDUM

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(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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#### OTHER QUALIFIED VERSIONS OF SN54LS112A, SN74LS112A:

Catalog: SN74LS112A

Military: SN54LS112A

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

## **PACKAGE MATERIALS INFORMATION**

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### TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

Device	Package Type	Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS112ADR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74LS112ANSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

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\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS112ADR	SOIC	D	16	2500	333.2	345.9	28.6
SN74LS112ANSR	SO	NS	16	2000	853.0	449.0	35.0

# FK (S-CQCC-N\*\*)

## LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. Falls within JEDEC MS-004



# D (R-PDS0-G16)

#### PLASTIC SMALL OUTLINE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.



# D (R-PDSO-G16)

## PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



#### **MECHANICAL DATA**

## NS (R-PDSO-G\*\*)

# 14-PINS SHOWN

#### PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



# W (R-GDFP-F16)

## CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP2-F16



### 14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

# N (R-PDIP-T\*\*)

## PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



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